SCLS020E - MARCH 1984 - REVISED AUGUST 2003

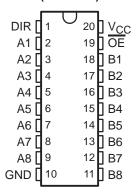
- Operating Voltage Range of 4.5 V to 5.5 V
- High-Current 3-State Outputs Drive Bus Lines Directly or Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 14 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Inputs Are TTL-Voltage Compatible

description/ordering information

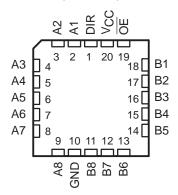
These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

The 'HCT245 devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so that the buses are effectively isolated.

SN54HCT245 . . . J OR W PACKAGE SN74HCT245 . . . DB, DW, N, NS, OR PW PACKAGE (TOP VIEW)



SN54HCT245 . . . FK PACKAGE (TOP VIEW)



ORDERING INFORMATION

| TA | PACKA | GE† | ORDERABLE PART NUMBER | TOP-SIDE MARKING | |
|----------------|------------|--------------|--------------------------|---------------------|--|
| | PDIP – N | Tube of 20 | SN74HCT245N | SN74HCT245N | |
| | SOIC - DW | Tube of 25 | SN74HCT245DW | HCT245 | |
| | 30IC - DVV | Reel of 2000 | SN74HCT245DWR | HC1245 | |
| -40°C to 85°C | SOP - NS | Reel of 2000 | SN74HCT245NSR | HCT245 | |
| -40 C to 65 C | SSOP - DB | Reel of 2000 | SN74HCT245DBR | HT245 | |
| | | Tube of 70 | SN74HCT245PW | | |
| | TSSOP - PW | Reel of 2000 | SN74HCT245PWR | HT245 | |
| | | Reel of 250 | SN74HCT245PWT | | |
| | CDIP – J | Tube of 20 | SNJ54HCT245J | SNJ54HCT245J | |
| −55°C to 125°C | CFP – W | Tube of 85 | SNJ54HCT245W | SNJ54HCT245W | |
| | LCCC – FK | Tube of 55 | SNJ54HCT245FK | SNJ54HCT245FK | |

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



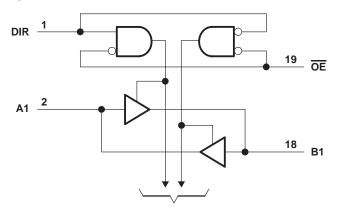
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



FUNCTION TABLE

| INP | UTS | OPERATION | | | | |
|-----|-----|-----------------|--|--|--|--|
| OE | DIR | OPERATION | | | | |
| L | L | B data to A bus | | | | |
| L | Н | A data to B bus | | | | |
| Н | Χ | Isolation | | | | |

logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| Supply voltage range, V _{CC} | | 0.5 V to 7 V |
|--|---|------------------|
| Input clamp current, IIK (VI < 0 or VI > VCC) (se | e Note 1) | ±20 mA |
| Output clamp current, IOK (VO < 0 or VO > VCO | c) (see Note 1) | ±20 mA |
| Continuous output current, I_O ($V_O = 0$ to V_{CC}) | • | ±35 mA |
| Continuous current through V _{CC} or GND | | ±70 mA |
| Package thermal impedance, θ_{JA} (see Note 2): | DB package | 70°C/W |
| | DW package | 58°C/W |
| | N package | 69°C/W |
| | NS package | 60°C/W |
| | PW package | 83°C/W |
| Storage temperature range, T _{sto} | | . −65°C to 150°C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 3)

| | | | SN | 54HCT2 | 45 | SN | 74HCT2 | 45 | UNIT |
|-------|---------------------------------|----------------------------------|-----|--------|-----|-----|--------|-----|------|
| | | | MIN | NOM | MAX | MIN | NOM | MAX | UNIT |
| VCC | Supply voltage | | 4.5 | 5 | 5.5 | 4.5 | 5 | 5.5 | V |
| VIH | High-level input voltage | V _{CC} = 4.5 V to 5.5 V | 2 | | | 2 | | | V |
| VIL | Low-level input voltage | V _{CC} = 4.5 V to 5.5 V | | | 0.8 | | | 0.8 | V |
| VI | Input voltage | | 0 | | VCC | 0 | | VCC | V |
| Vo | Output voltage | | 0 | | VCC | 0 | | VCC | V |
| Δt/Δν | Input transition rise/fall time | | | | 500 | | | 500 | ns |
| TA | Operating free-air temperature | | -55 | | 125 | -40 | | 85 | °C |

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| DAD | AMETER | TEST CONDITIONS | | Vaa | Т | A = 25°C | ; | SN54HCT245 | | SN74HCT245 | | UNIT | |
|------------------|-----------|--------------------------------------|--------------------------|-------------------|------|----------|------|------------|-------|------------|-------|------|--|
| FAR | AWETER | 1231 00 | NDITIONS | Vcc | MIN | TYP | MAX | MIN | MAX | MIN | MAX | ONIT | |
| Va | | \\ \\ or \\ | $I_{OH} = -20 \mu A$ | 4.5 V | 4.4 | 4.499 | | 4.4 | | 4.4 | | V | |
| VOH | | $V_I = V_{IH} \text{ or } V_{IL}$ | $I_{OH} = -6 \text{ mA}$ | 4.5 V | 3.98 | 4.3 | | 3.7 | | 3.84 | | V | |
| Val | | \\ \\ or \\ | I _{OL} = 20 μA | 4.5 V | | 0.001 | 0.1 | | 0.1 | | 0.1 | V | |
| VOL | | $V_I = V_{IH} \text{ or } V_{IL}$ | I _{OL} = 6 mA | 4.5 V | | 0.17 | 0.26 | | 0.4 | | 0.33 | v | |
| П | DIR or OE | $V_I = V_{CC}$ or 0 | | 5.5 V | | ±0.1 | ±100 | | ±1000 | | ±1000 | nA | |
| loz | A or B | VO = VCC or 0 | | 5.5 V | | ±0.01 | ±0.5 | | ±10 | | ±5 | μΑ | |
| Icc | | $V_I = V_{CC}$ or 0, | I _O = 0 | 5.5 V | | | 8 | | 160 | | 80 | μΑ | |
| ∆lcc† | | One input at 0.5 \ Other inputs at 0 | | 5.5 V | | 1.4 | 2.4 | | 3 | | 2.9 | mA | |
| C _i ‡ | DIR or OE | | | 4.5 V to 5.5 V | | 3 | 10 | | 10 | | 10 | pF | |

[†] This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM | FROM TO | | T, | T _A = 25°C | | SN54HCT245 | | SN74HCT245 | | UNIT |
|------------------|--|---------|-------|-----|-----------------------|-----|------------|-----|------------|-----|------|
| PARAMETER | (INPUT) (OUTPUT) | | VCC | MIN | TYP | MAX | MIN | MAX | MIN | MAX | UNIT |
| | A or B | B or A | 4.5 V | | 16 | 22 | | 33 | | 28 | ns |
| ^t pd | AOIB | B or A | 5.5 V | | 14 | 20 | | 30 | | 25 | 110 |
| + | t _{en} $\overline{\text{OE}}$ | A or B | 4.5 V | | 25 | 46 | | 69 | | 58 | ns |
| ^t en | | | 5.5 V | | 22 | 41 | | 62 | | 52 | |
| + | ŌĒ | A or B | 4.5 V | | 26 | 40 | | 60 | | 50 | ns |
| ^t dis | OE | A or B | 5.5 V | | 23 | 36 | | 54 | | 45 | 110 |
| 4. | | A == D | 4.5 V | | 9 | 12 | | 18 | | 15 | ns |
| t _t | | A or B | 5.5 V | | 8 | 11 | | 16 | | 14 | |

[‡] Parameter C_i does not apply to transceiver I/O ports.

SN54HCT245, SN74HCT245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

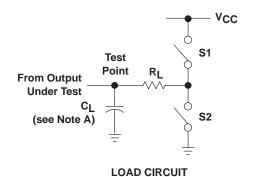
| PARAMETER | FROM | то | Voc | T _A = 25°C | | | SN54HCT245 | | SN74HCT245 | | UNIT |
|-----------------|---------|----------|-------|-----------------------|-----|-----|------------|-----|------------|-----|------|
| PARAMETER | (INPUT) | (OUTPUT) | VCC | MIN | TYP | MAX | MIN | MAX | MIN | MAX | UNIT |
| + . | A or B | B or A | 4.5 V | | 20 | 30 | | 45 | | 38 | ns |
| ^t pd | AOID | BUIA | 5.5 V | | 18 | 27 | | 41 | | 34 | 115 |
| | ŌĒ | A or B | 4.5 V | | 36 | 59 | | 89 | | 74 | no |
| t _{en} | OE | | 5.5 V | | 30 | 53 | | 80 | | 67 | ns |
| | | A or B | 4.5 V | | 17 | 42 | | 63 | | 53 | |
| t _t | | | 5.5 V | | 14 | 38 | | 57 | | 48 | ns |

operating characteristics, $T_A = 25^{\circ}C$

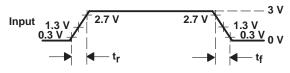
| | PARAMETER | TEST CONDITIONS | TYP | UNIT |
|-----------------|---|-----------------|-----|------|
| C _{pd} | Power dissipation capacitance per transceiver | No load | 40 | pF |



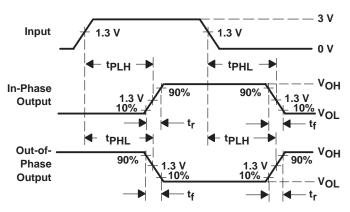
PARAMETER MEASUREMENT INFORMATION

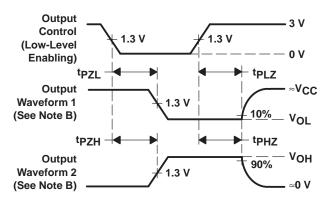


| PARAN | /IETER | RL | CL | S1 | S2 | |
|--------------------|------------------------------|--------------|-----------------------|--------|--------|--|
| | tPZH | 1 k Ω | 50 pF or | Open | Closed | |
| ten ' | tPZL | 1 K22 | 150 pF | Closed | Open | |
| 4 | tPHZ | 1 k Ω | 50 pF | Open | Closed | |
| ^t dis | t_{PLZ} 1 k Ω 50 pF | | 30 pr | Closed | Open | |
| t _{pd} or | t _t | _ | 50 pF or 150 pF | Open | Open | |



VOLTAGE WAVEFORM INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT RISE AND FALL TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms









PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|-----------------|--------------------|------|----------------|-------------------|------------------|--|
| 5962-8550601VRA | ACTIVE | CDIP | J | 20 | 1 | TBD | Call TI | Level-NC-NC-NC |
| 5962-8550601VSA | ACTIVE | CFP | W | 20 | 1 | TBD | Call TI | Level-NC-NC-NC |
| 85506012A | ACTIVE | LCCC | FK | 20 | 1 | TBD | Call TI | Level-NC-NC-NC |
| 8550601RA | ACTIVE | CDIP | J | 20 | 1 | TBD | Call TI | Level-NC-NC-NC |
| JM38510/65553BRA | ACTIVE | CDIP | J | 20 | 1 | TBD | Call TI | Level-NC-NC-NC |
| JM38510/65553BSA | ACTIVE | CFP | W | 20 | 1 | TBD | Call TI | Level-NC-NC-NC |
| SN54HCT245J | ACTIVE | CDIP | J | 20 | 1 | TBD | Call TI | Level-NC-NC-NC |
| SN74HCT245DBLE | OBSOLETE | SSOP | DB | 20 | | TBD | Call TI | Call TI |
| SN74HCT245DBR | ACTIVE | SSOP | DB | 20 | 2000 | Pb-Free (RoHS) | CU NIPDAU | Level-2-260C-1 YEAR/ Level-1-235C-UNLIM |
| SN74HCT245DW | ACTIVE | SOIC | DW | 20 | 25 | Pb-Free (RoHS) | CU NIPDAU | Level-2-250C-1 YEAR/ Level-1-235C-UNLIM |
| SN74HCT245DWR | ACTIVE | SOIC | DW | 20 | 2000 | Pb-Free (RoHS) | CU NIPDAU | Level-2-250C-1 YEAR/ Level-1-235C-UNLIM |
| SN74HCT245N | ACTIVE | PDIP | N | 20 | 20 | Pb-Free (RoHS) | CU NIPDAU | Level-NC-NC-NC |
| SN74HCT245N3 | OBSOLETE | PDIP | N | 20 | | TBD | Call TI | Call TI |
| SN74HCT245NSR | ACTIVE | SO | NS | 20 | 2000 | Pb-Free (RoHS) | CU NIPDAU | Level-2-260C-1 YEAR/ Level-1-235C-UNLIM |
| SN74HCT245PW | ACTIVE | TSSOP | PW | 20 | 70 | Pb-Free (RoHS) | CU NIPDAU | Level-1-250C-UNLIM |
| SN74HCT245PWLE | OBSOLETE | TSSOP | PW | 20 | | TBD | Call TI | Call TI |
| SN74HCT245PWR | ACTIVE | TSSOP | PW | 20 | 2000 | Pb-Free (RoHS) | CU NIPDAU | Level-1-250C-UNLIM |
| SN74HCT245PWT | ACTIVE | TSSOP | PW | 20 | 250 | Pb-Free (RoHS) | CU NIPDAU | Level-1-250C-UNLIM |
| SNJ54HCT245FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | Call TI | Level-NC-NC-NC |
| SNJ54HCT245J | ACTIVE | CDIP | J | 20 | 1 | TBD | Call TI | Level-NC-NC-NC |
| SNJ54HCT245W | ACTIVE | CFP | W | 20 | 1 | TBD | Call TI | Level-NC-NC-NC |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

30-Mar-2005

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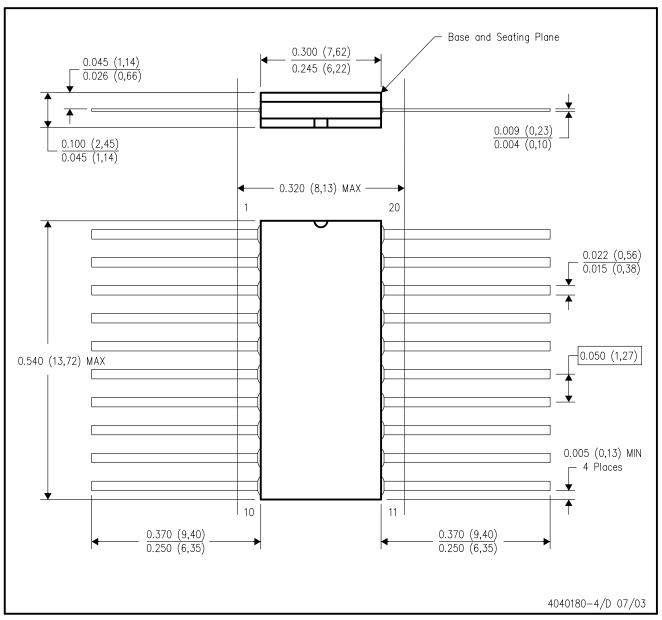
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



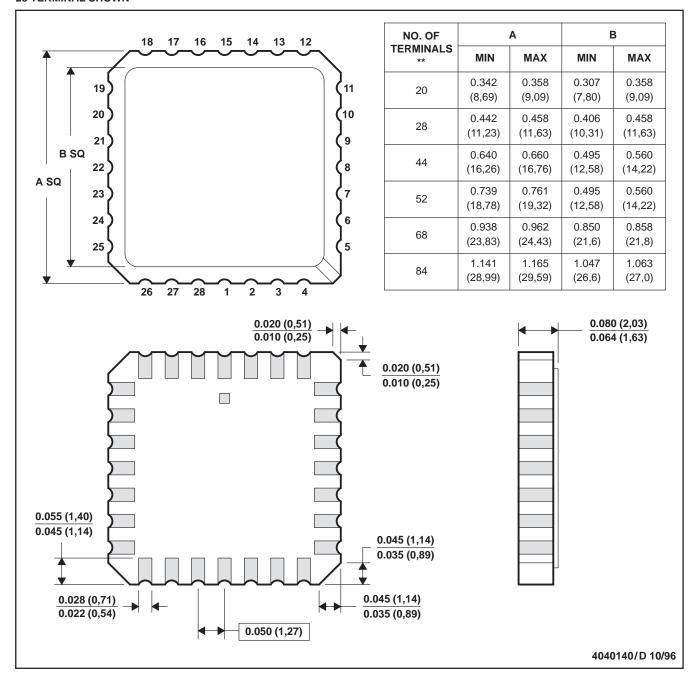
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

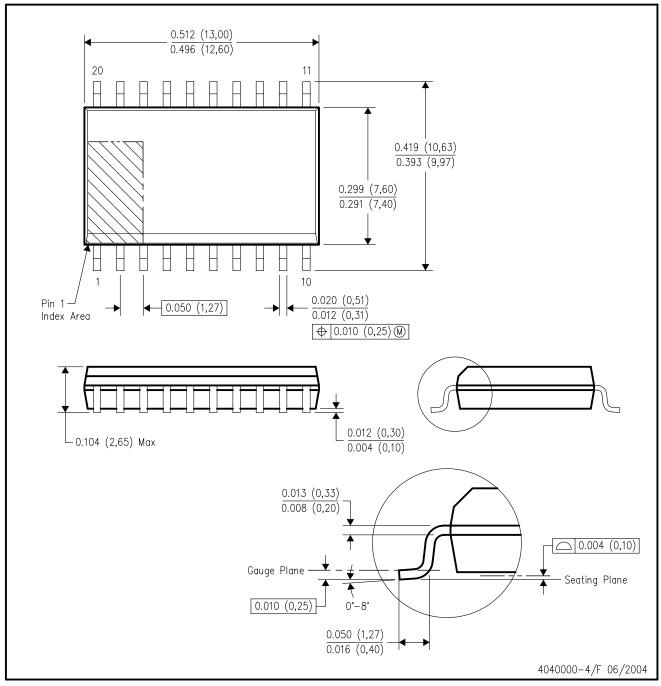


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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